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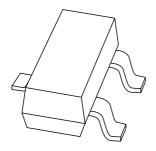
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Kind regards,

Team Nexperia

# **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# **BF550**PNP medium frequency transistor

Product data sheet Supersedes data of 1999 Apr 15 2004 Jan 16



NXP Semiconductors Product data sheet

# PNP medium frequency transistor

**BF550** 

#### **FEATURES**

- Low current (max. 25 mA)
- Low voltage (max. 40 V).

#### **APPLICATIONS**

Medium frequency applications in thick and thin film circuits.

#### **DESCRIPTION**

PNP medium frequency transistor in a SOT23 plastic package.

#### **MARKING**

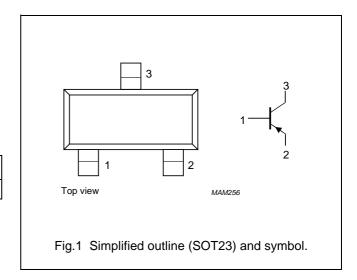
| TYPE NUMBER | MARKING CODE(1) |  |
|-------------|-----------------|--|
| BF550       | LA*             |  |

#### Note

\* = p : Made in Hong Kong.
 \* = t : Made in Malaysia.
 \* = W : Made in China.

#### **PINNING**

| PIN | DESCRIPTION |
|-----|-------------|
| 1   | base        |
| 2   | emitter     |
| 3   | collector   |



#### **ORDERING INFORMATION**

| TYPE   |      | PACKAGE                                  |       |  |  |
|--------|------|--|-------|--|--|
| NUMBER | NAME | DESCRIPTION VERSION                      |       |  |  |
| BF550  | _    | plastic surface mounted package; 3 leads | SOT23 |  |  |

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| SYMBOL           | PARAMETER                     | CONDITIONS                       | MIN. | MAX. | UNIT |
|------------------|-------------------------------|----------------------------------|------|------|------|
| V <sub>CBO</sub> | collector-base voltage        | open emitter                     | _    | -40  | V    |
| V <sub>CEO</sub> | collector-emitter voltage     | open base                        | _    | -40  | V    |
| V <sub>EBO</sub> | emitter-base voltage          | open collector                   | _    | -4   | V    |
| I <sub>C</sub>   | collector current (DC)        |                                  | _    | -25  | mA   |
| I <sub>CM</sub>  | peak collector current        |                                  | _    | -25  | mA   |
| P <sub>tot</sub> | total power dissipation       | T <sub>amb</sub> ≤ 25 °C; note 1 | _    | 250  | mW   |
| T <sub>stg</sub> | storage temperature           |                                  | -65  | +150 | °C   |
| Tj               | junction temperature          |                                  | _    | 150  | °C   |
| T <sub>amb</sub> | operating ambient temperature |                                  | -65  | +150 | °C   |

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

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#### THERMAL CHARACTERISTICS

| SYMBOL               | PARAMETER                                   | CONDITIONS | VALUE | UNIT |
|----------------------|---|------------|-------|------|
| R <sub>th(j-a)</sub> | thermal resistance from junction to ambient | note 1     | 500   | K/W  |

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

#### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

| SYMBOL           | PARAMETER                 | CONDITIONS   | MIN. | TYP. | MAX. | UNIT |
|------------------|---------------------------|--|------|------|------|------|
| I <sub>CBO</sub> | collector cut-off current | $I_E = 0; V_{CB} = -30 \text{ V}$  | _    | _    | -50  | nA   |
| I <sub>EBO</sub> | emitter cut-off current   | $I_C = 0; V_{EB} = -3 \text{ V}$   | _    | _    | -100 | nA   |
| h <sub>FE</sub>  | DC current gain           | $I_C = -1 \text{ mA}; V_{CE} = -10 \text{ V}$                            | 50   | _    | _    |      |
| $V_{BE}$         | base-emitter voltage      | $I_C = -1 \text{ mA}; V_{CE} = -10 \text{ V}$                            | _    | 750  | _    | mV   |
| C <sub>re</sub>  | feedback capacitance      | $I_C = -1 \text{ mA}; V_{CB} = -10 \text{ V}; f = 1 \text{ MHz}$         | _    | 0.5  | _    | pF   |
| f <sub>T</sub>   | transition frequency      | $I_C = -1 \text{ mA}$ ; $V_{CE} = -10 \text{ V}$ ; $f = 100 \text{ MHz}$ | _    | 325  | _    | MHz  |

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# PNP medium frequency transistor

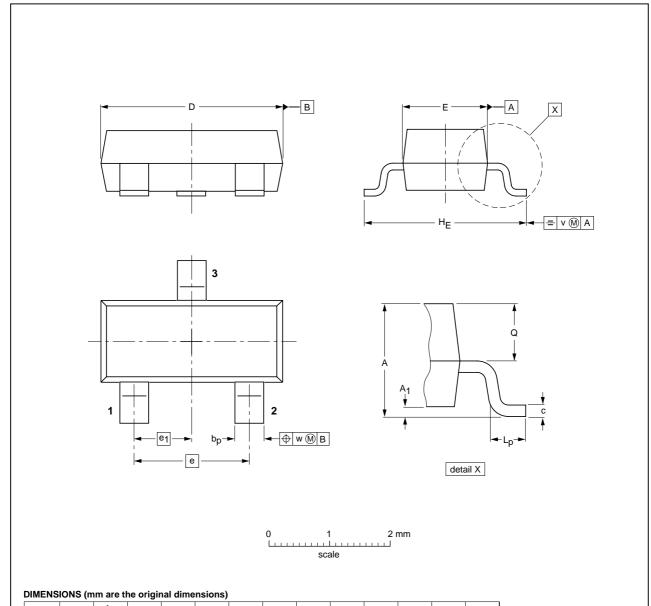
BF550

#### **PACKAGE OUTLINE**

UNIT

#### Plastic surface-mounted package; 3 leads

SOT23



| OUTLINE | REFERENCES |          | EUROPEAN | ISSUE DATE |                       |                                  |
|---------|------------|----------|----------|------------|-----------------------|----------------------------------|
| VERSION | IEC        | JEDEC    | JEITA    |            | PROJECTION ISSUE DATE |                                  |
| SOT23   |            | TO-236AB |          |            |                       | <del>-04-11-04</del><br>06-03-16 |

 $\mathsf{H}_{\mathsf{E}}$ 

 $\mathbf{L}_{\mathbf{p}}$ 

0.45

0.55

0.1

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bp

0.38

max

0.9

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### PNP medium frequency transistor

BF550

#### **DATA SHEET STATUS**

| DOCUMENT<br>STATUS <sup>(1)</sup> | PRODUCT<br>STATUS <sup>(2)</sup> | DEFINITION  |
|-----------------------------------|----------------------------------|---|
| Objective data sheet              | Development                      | This document contains data from the objective specification for product development. |
| Preliminary data sheet            | Qualification                    | This document contains data from the preliminary specification.                       |
| Product data sheet                | Production                       | This document contains the product specification.                                     |

#### **Notes**

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## **NXP Semiconductors**

#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

For additional information please visit: http://www.nxp.com
For sales offices addresses send e-mail to: salesaddresses@nxp.com

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